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Many industrial and automotive applications use the synchronous buck converter power-supply topology; these applications also require low conducted and radiated emissions to ensure that the power supply does not interfere with other equipment sharing the same bus (input voltage V_{IN}). For example, in an automotive infotainment system, electromagnetic interference (EMI) could result in unwanted noise in the car stereo.

Figure 1 shows a synchronous buck-converter schematic, along with its switch-node waveform. The ringing on the peak of the switch-node waveform is a function of both the high-side MOSFET's switching speed and the high-side and low-side MOSFETs and printed circuit boards (PCB) stray inductance and capacitance. The ringing on the switch-node waveform is unwanted because it can increase the voltage stress on the low-side MOSFET and generate EMI.

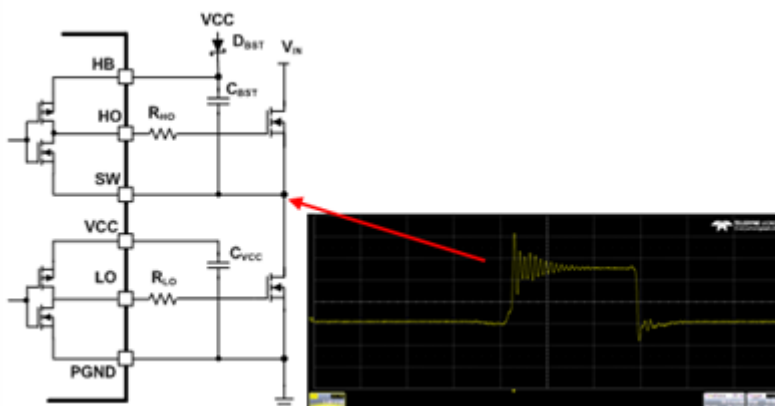


Figure 1. Synchronous Buck Converter

To determine the relationship between the switch-node ringing of the buck converter in Figure 1 and the EMI that it generates, I ran conducted emissions testing in accordance with Comité International Spécial des Perturbations Radioélectriques (CISPR) 25 Class 5. Figure 2 shows the results. The measured data shows that the buck converter's conducted emissions exceed Class 5 limits by 15dB μ V in the 30MHz-108MHz frequency range.

The losses in the low-side MOSFET include $R_{DS(ON)}$ losses, dead-time losses and losses in the MOSFET's internal body diode. During the dead time (when the high- and low-side MOSFETs are turned off) the low-side MOSFET's internal body diode conducts the inductor current. The MOSFET's internal body diodes typically have a high forward-voltage drop, so there can be a significant reduction in efficiency. Reducing the time that the low-side MOSFET's internal body diode conducts current improves efficiency.

Using slew-rate control, a resistor (R_{OL}) can be inserted between the LM5140-Q1 driver output (LO pin) and the low-side MOSFETs gate to increase the time that it takes for the low-side MOSFET to turn-off. Slowing down the turn-off time decreases the dead time between the low- and high-side MOSFETs' conduction, increasing buck-converter efficiency. When reducing the dead time for a synchronous buck, make sure that the high- and low-side MOSFETs never conduct at the same time.

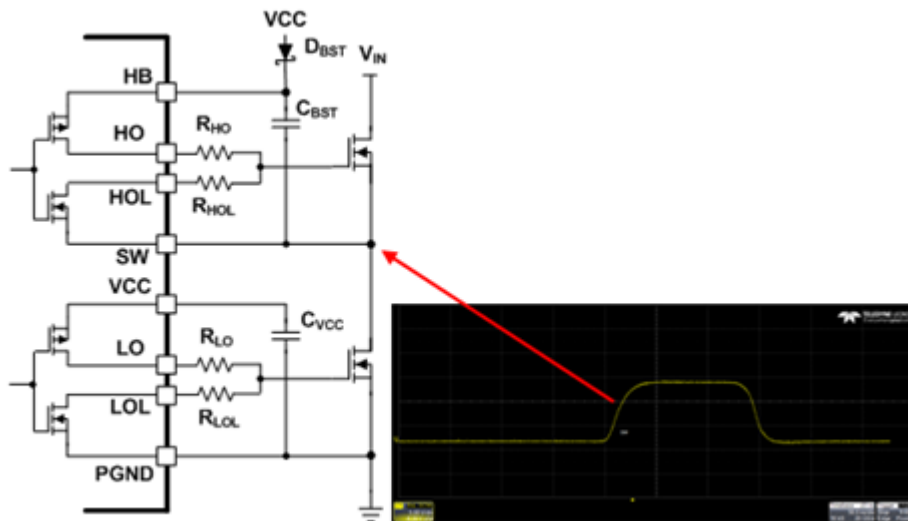


Figure 4: Buck converter switch-node waveform with slew-rate control

I modified the power supply shown in [Figure 1](#) using the LM5140-Q1 controller (see [Figure 4](#)). Using slew-rate control optimizes the switch-node rise and fall time, eliminating switch-node ringing.

The next step is to run the CISPR 25 Class 5 conducted emissions. I chose these slew-rate control-resistor values: $R_{HO} = 10\Omega$, $R_{HOL} = 0\Omega$, $R_{LO} = 10\Omega$ and $R_{LOL} = 10\Omega$. The resistors I selected for this application are a good startup point for any application where the output power is under 50W.

[Figure 3](#) shows the results and summary of the conducted emissions testing.

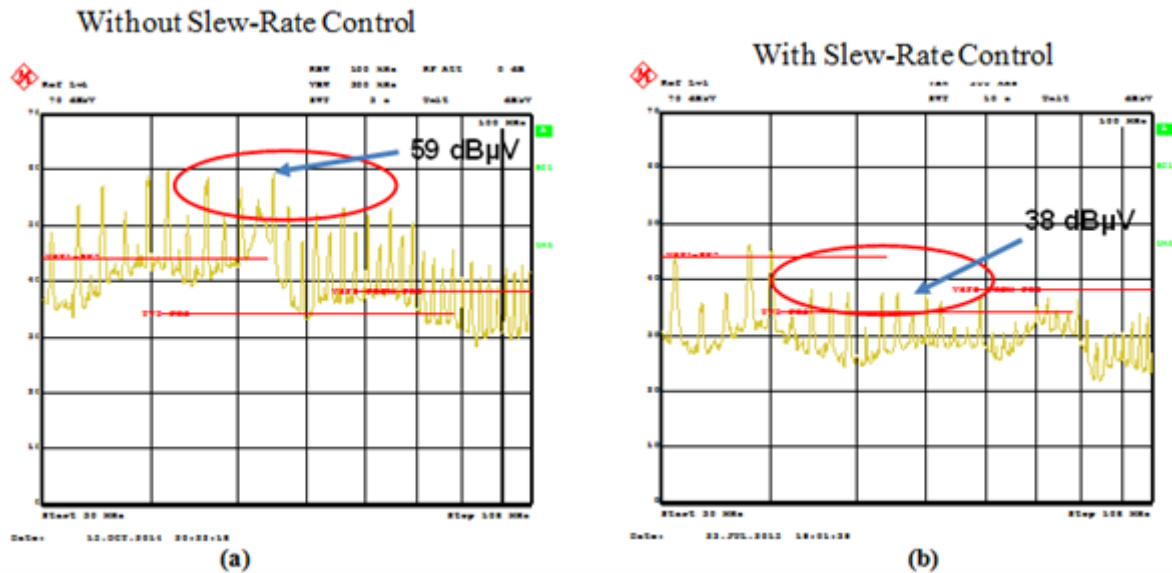


Figure 3. Slew-rate Control Comparison: CISPR 25 Class 5, $v_{IN} = 12V$, $v_{OUT} = 3.3V$, $I_{OUT} = 5A$, without Slew-rate Control (a) and with Slew-rate Control (b)

The buck converter using the LM5140-Q1 with slew-rate control reduced conducted emissions by 21dB μ V. It also provided better control of the switch-node rise and fall and eliminated the need for a snubber circuit, which adds circuit complexity and cost.

By picking the correct values of slew-rate control resistors, not only can you reduce EMI; you can also improve system efficiency.

See a live demonstration of the LM5140-Q1 buck converter in TI's booth (No. 1617) at the Applied Power Electronics Conference (APEC), March 21-23 in Long Beach, California. Follow TI at www.ti.com/apec2016.

Additional Resources

- Watch the video “[Engineer it: How to use slew rate control for EMI reduction.](#)”
- See the [LM5140-Q1 data sheet](#).
- Open the “[LM5140-Q1 Evaluation Module User's Guide.](#)”

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